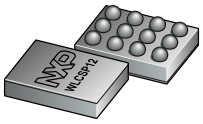


SOT1390-7

WLCSP12, wafer level chip-scale package; 12 bumps; 1.67 mm x 1.27 mm x 0.525 mm (backside coating included)

23 November 2021 Package information

1 Package summary

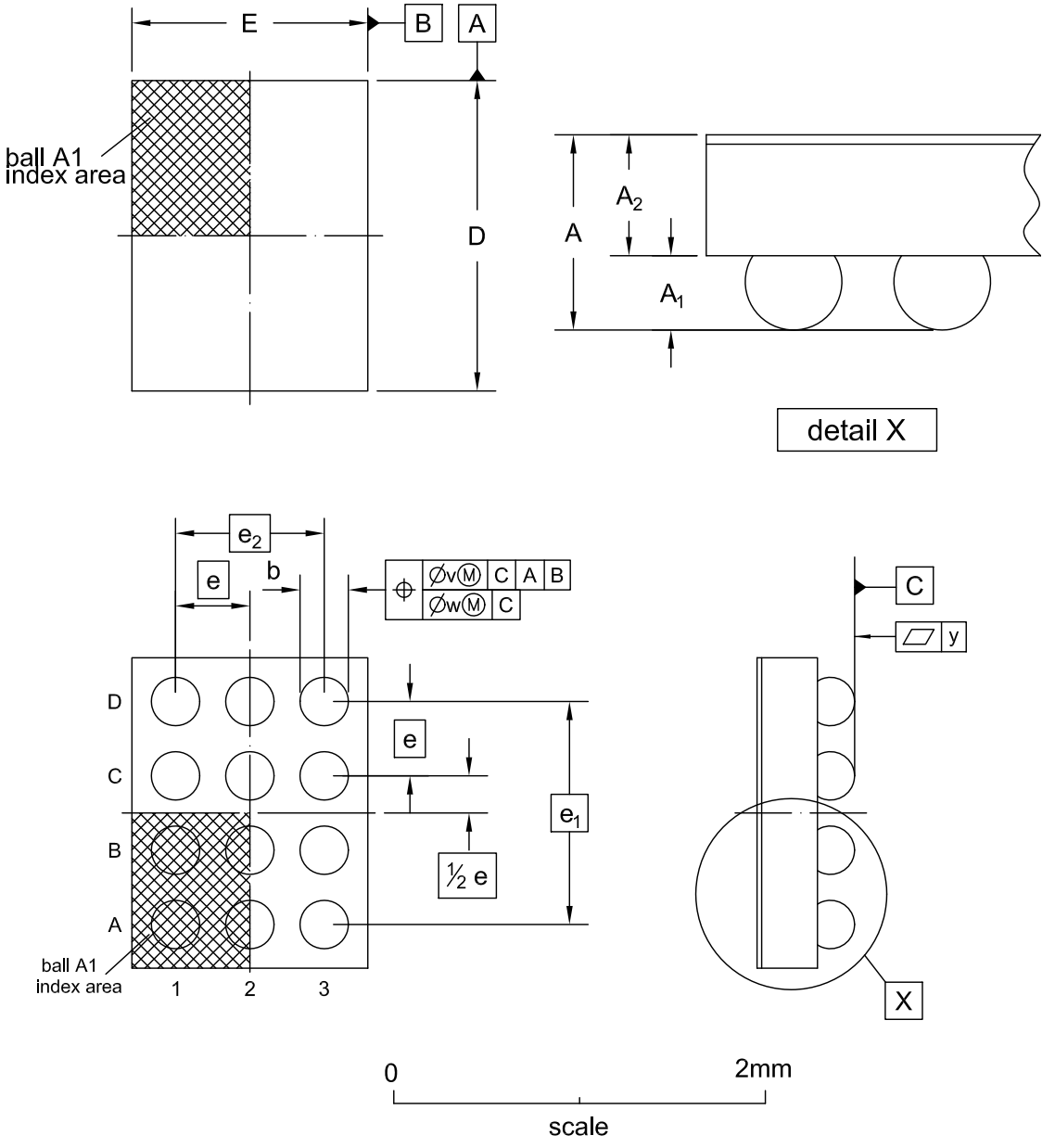
Terminal position code	B (bottom)
Package type descriptive code	WLCSP12
Package type industry code	WLCSP12
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	24-04-2017
Manufacturer package code	SOT1390

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.64	1.67	1.7	mm
package width	1.24	1.27	1.3	mm
seated height	0.485	0.525	0.565	mm
package height	0.3	0.325	0.35	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	12	-	

WLCSP12, wafer level chip-scale package; 12 bumps; 1.67 mm x 1.27 mm x 0.525 mm (backside coating included)

2 Package outline



DIMENSIONS (mm are the original dimensions)

UNIT		A	A_1	A_2	b	D	E	e	e_1	e_2	v	w	y
mm	MAX.	0.565	0.23	0.350	0.29	1.70	1.30	0.4	1.2	0.8	0.05	0.02	0.03
	NOM.	0.525	0.20	0.325	0.26	1.67	1.27						
	MIN.	0.485	0.17	0.300	0.23	1.64	1.24						

NOTE: Backside coating 25 um

Figure 1. Package outline WLCSP12 (SOT1390-7)

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3 Soldering

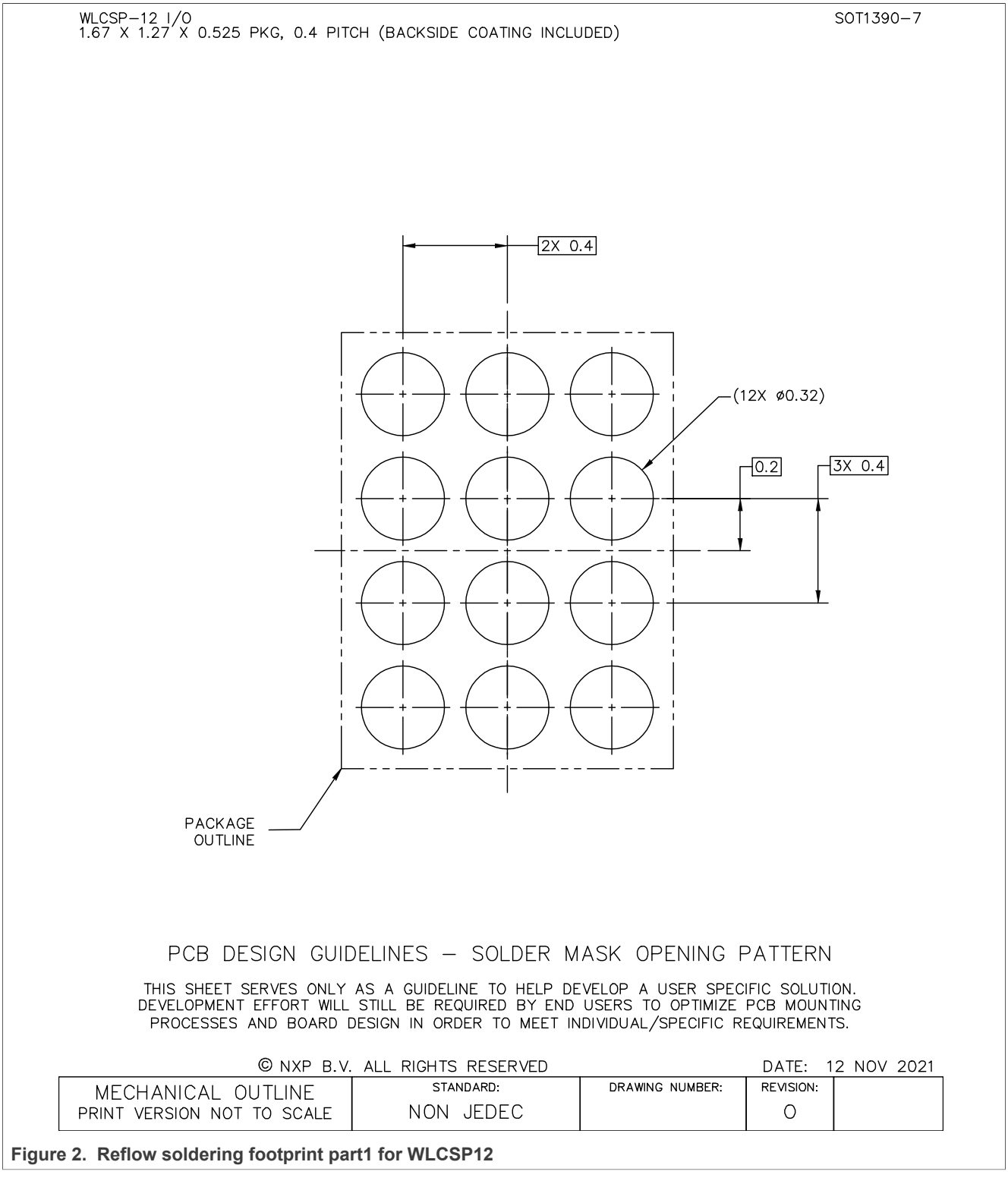

Figure 2. Reflow soldering footprint part1 for WLCSP12

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WLCSP12, wafer level chip-scale package; 12 bumps; 1.67 mm x 1.27 mm x 0.525 mm (backside coating included)

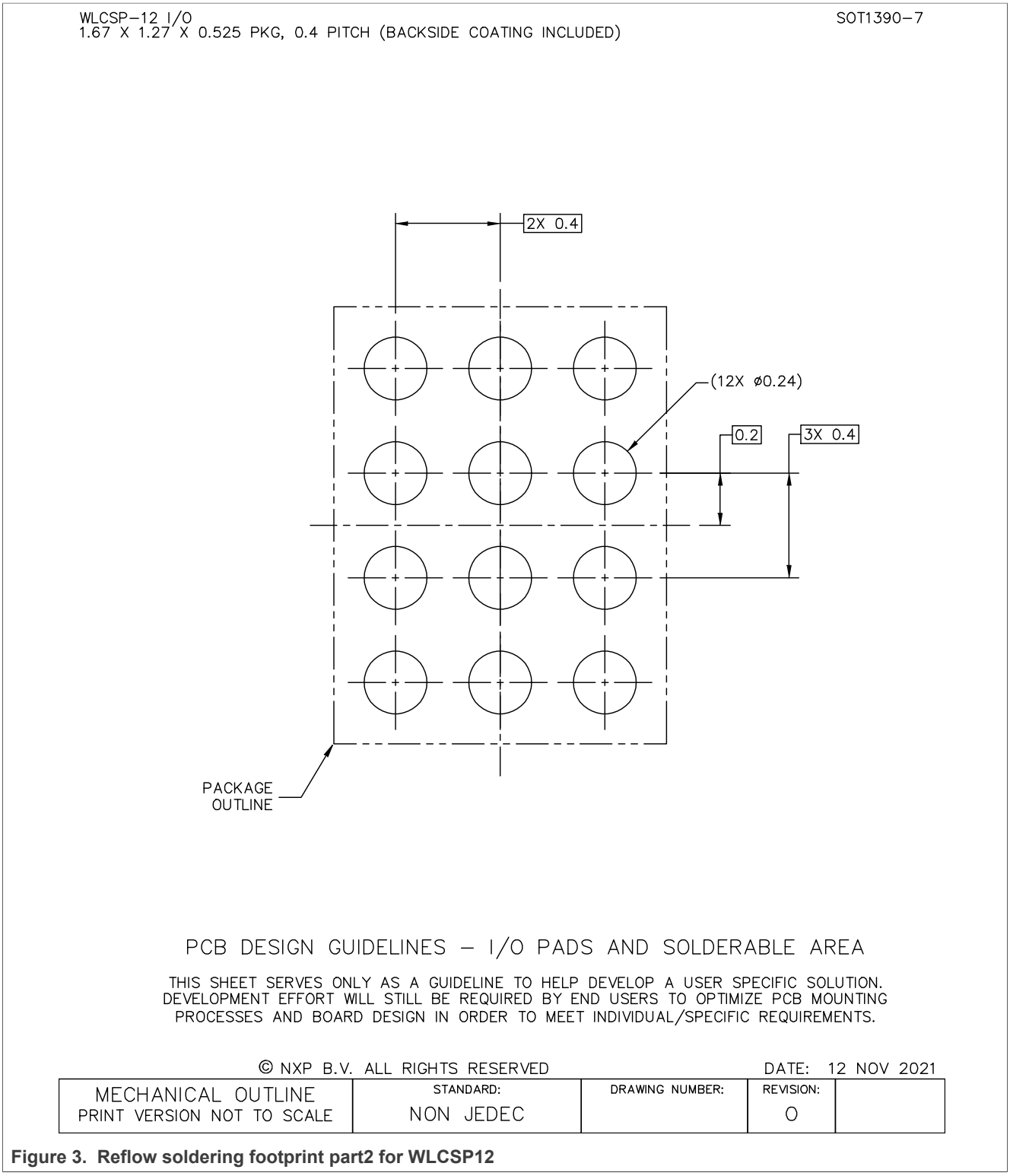

Figure 3. Reflow soldering footprint part2 for WLCSP12

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WLCSP12, wafer level chip-scale package; 12 bumps; 1.67 mm x 1.27 mm x 0.525 mm (backside coating included)

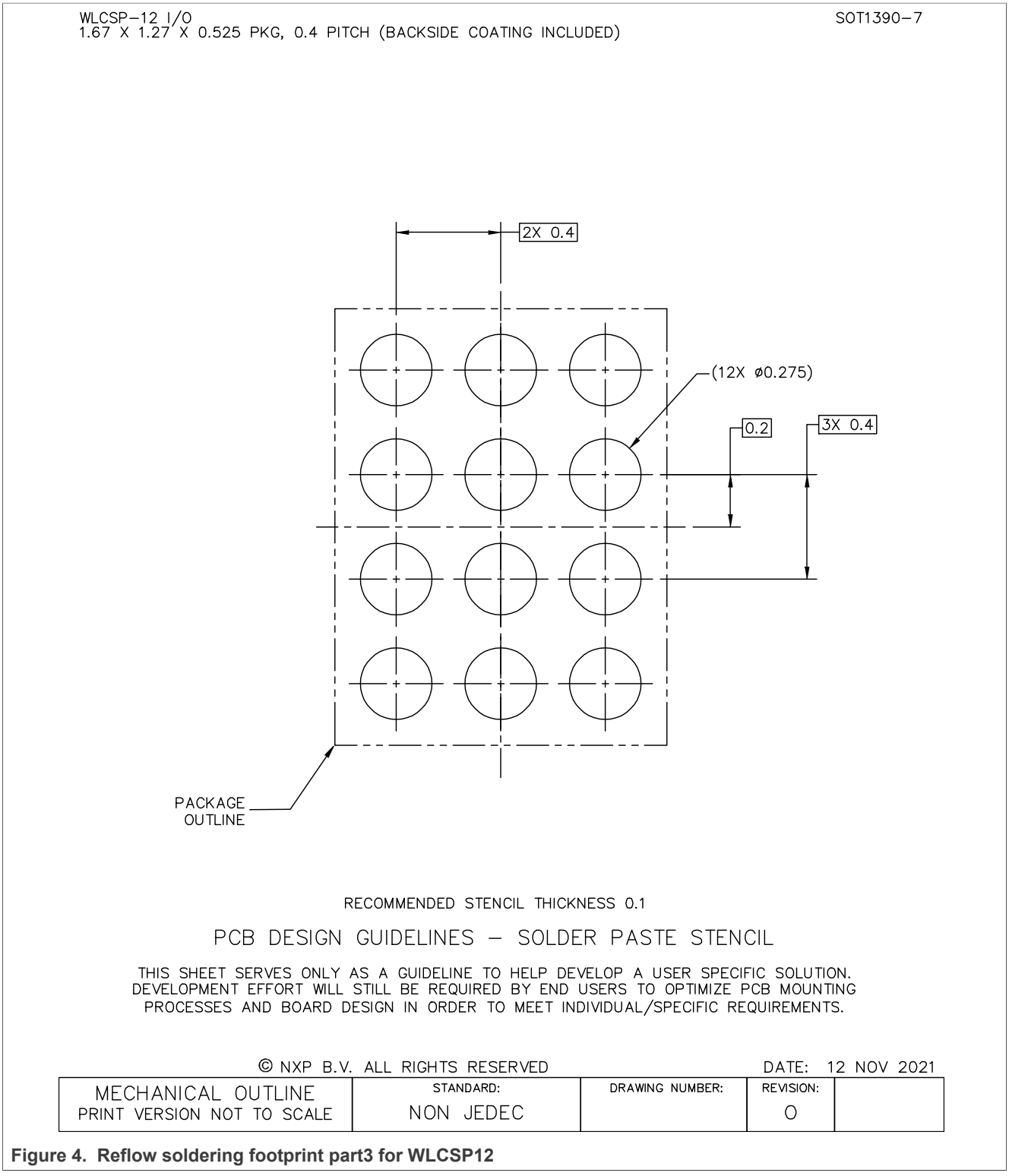

Figure 4. Reflow soldering footprint part3 for WLCSP12

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4 Legal information

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WLCSP12, wafer level chip-scale package; 12 bumps; 1.67 mm x 1.27 mm x 0.525 mm (backside coating included)

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Date of release: 23 November 2021